



Japanese Fabs Examine Wafer-Processing Metrology at New Japanese-Language Website From CyberOptics Semiconductor, Inc. -- <http://jp.cyberopticssemi.com/>

Japanese Fabs “Chiefly Concerned” With Effects of Vibration On Wafer-Handling Equipment, According to Company

BEPPU-CITY, Japan and BEAVERTON, Ore., Sept. 15, 2008 – A maker of [metrology devices for wafer processing equipment](#), CyberOptics Semiconductor, Inc., has launched a Japanese-language version of its Website after engineers at various Japanese fabs recently called on the Oregon-based company to translate its site with pages dedicated to wafer-processing metrology, according to Yukinobu Hayashi, a field applications engineer for the company.

Hayashi said CyberOptics Semiconductor’s new [Japanese-language site](#) -- <http://jp.cyberopticssemi.com/> -- will help the company support and field queries from Japanese fabs that manufacture a range of devices for memory, logic, analog and optical applications.

Of the more than 100 fabs in Japan, about 25 percent of them are 200 mm and approximately 12 percent are 300 mm fabs, according to Hayashi. Process engineers at 200 mm fabs in Japan tend to look to wafer-processing metrology to “maximize their equipment,” while engineers at 300 mm fabs often look to metrology for “advancing automation,” Hayashi said.

Engineers at CyberOptics Semiconductor, a subsidiary of CyberOptics Corp. (Nasdaq:CYBE), have found that Japanese fabs are “chiefly concerned” with equipment acceleration and vibration and their relationship to [downtime and wafer particle contamination](#), Hayashi said.

“Japanese manufacturers are always looking at ways to improve productivity at 200 and 300 mm fabs, particularly as the industry looks to 32 nm node and 450 mm geometries,” Hayashi said. “And in terms of wafer-processing metrology, they’re most interested in vibration.”

Hayashi added that OEM toolmakers in Japan have been “quick to evaluate” CyberOptics Semiconductor’s device that measures three axis (x, y, z) [wafer-transfer coordinates for teaching robots](#), the WaferSense(tm) Auto Teaching System (ATS).

CyberOptics Semiconductor essentially translated its entire site, including various product pages and its resource center page. The resource page includes links to answers to frequently asked questions, or FAQs, on its [wireless metrology devices](#) for teaching, leveling and gapping wafer-processing equipment, as well as its reflective wafer-mapping sensors.

Visitors to CyberOptics Semiconductor’s primary Website will find a Japanese flag atop the home page that takes them to the newly translated site.

CyberOptics Semiconductor’s wireless WaferSense family of products includes the Auto Vibration System (AVS), Auto Leveling System (ALS), Auto Teaching System (ATS) and Auto Gapping System (AGS). Each device follows the processing life of a wafer.

About CyberOptics Semiconductor, Inc.

CyberOptics Semiconductor develops automated products that seamlessly measure critical parameters in semiconductor fabrication processes and equipment. The company's pioneering WaferSense(tm) line includes wireless metrology devices for vibration, leveling, gapping and teaching semiconductor process equipment. The company is the largest producer of [reflective wafer-mapping sensors](#) and a leading provider of [frame grabber machine vision boards](#) under its HAMA Sensors(tm) and Imagenation(tm) brands. CyberOptics Semiconductor is a subsidiary of CyberOptics Corp. (Nasdaq:CYBE), one of the world's leading providers of process yield and throughput improvement solutions for electronic assembly and semiconductor capital equipment companies. For information, visit <http://www.cyberopticssemi.com/>, e-mail CSales@cyberoptics.com or call 800-366-9131.

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